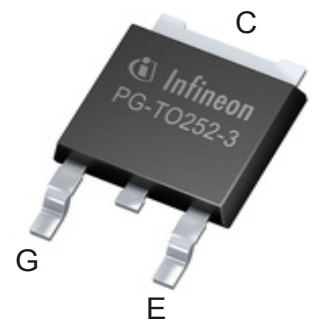
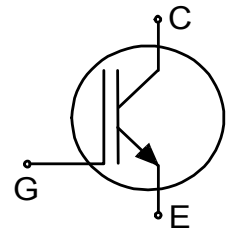


TRENCHSTOP™ IGBT6

IGBT in trench and field-stop technology

Features and Benefits:

- Very low $V_{CE(sat)}$ 1.5V (typ.)
 - Maximum junction temperature 175°C
 - Short circuit withstand time 3μs
- Trench and field-stop technology for 650V applications offers :
- very tight parameter distribution
 - high ruggedness, temperature stable behavior
 - low V_{CEsat} and positive temperature coefficient
 - Low gate charge Q_G
 - Pb-free lead plating; RoHS compliant
 - Complete product spectrum and PLECS Models:
- www.infineon.com/igbt



Potential Applications:

Drives

- GPD (general purpose drives)

Major home appliances

- Air conditioning
- Other major home appliances

Small home appliances

- Other small home appliances

Product Validation:

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22



Key Performance and Package Parameters

Type	V_{CE}	I_C	V_{CEsat} , $T_{vj}=25^{\circ}C$	T_{vjmax}	Marking	Package
IGD10N65T6	650V	10A	1.5V	175°C	G10ET6	PG-TO252-3

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TRENCHSTOP™ IGBT6

Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj} \geq 25^{\circ}\text{C}$	V_{CE}	650	V
DC collector current, limited by T_{vjmax} $T_c = 25^{\circ}\text{C}$ $T_c = 100^{\circ}\text{C}$	I_C	23.0 14.0	A
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpuls}	42.5	A
Turn off safe operating area $V_{CE} \leq 650\text{V}$, $T_{vj} \leq 175^{\circ}\text{C}$	-	42.5	A
Gate-emitter voltage Transient Gate-emitter voltage ($t_p \leq 10\mu\text{s}$, $D < 0.010$)	V_{GE}	± 20 ± 30	V
Short circuit withstand time $V_{GE} = 15.0\text{V}$, $V_{CC} \leq 360\text{V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{s}$ $T_{vj} = 150^{\circ}\text{C}$	t_{SC}	3	μs
Power dissipation $T_c = 25^{\circ}\text{C}$ Power dissipation $T_c = 100^{\circ}\text{C}$	P_{tot}	75.0 37.5	W
Operating junction temperature	T_{vj}	$-40 \dots +175$	$^{\circ}\text{C}$
Storage temperature	T_{stg}	$-55 \dots +150$	$^{\circ}\text{C}$
Soldering temperature, reflow soldering (MSL1 according to JEDEC J-STA-020)		260	$^{\circ}\text{C}$

Thermal Resistance

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
R _{th} Characteristics						
IGBT thermal resistance, junction - case	R _{th(j-c)}		-	-	2.00	K/W
Thermal resistance, min. footprint junction - ambient	R _{th(j-a)}		-	-	75	K/W
Thermal resistance, 6cm ² Cu on PCB junction - ambient	R _{th(j-a)}		-	-	50	K/W

Electrical Characteristic, at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE} = 15.0V, I_C = 8.5A$ $T_{vj} = 25^{\circ}C$ $T_{vj} = 125^{\circ}C$ $T_{vj} = 150^{\circ}C$	- - -	1.50 1.65 1.75	1.90 - -	V
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 0.15mA, V_{CE} = V_{GE}$	4.8	5.6	6.4	V
Zero gate voltage collector current	I_{CES}	$V_{CE} = 650V, V_{GE} = 0V$ $T_{vj} = 25^{\circ}C$ $T_{vj} = 150^{\circ}C$	- -	- 360	30 -	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0V, V_{GE} = 20V$	-	-	100	nA
Transconductance	g_{fs}	$V_{CE} = 20V, I_C = 8.5A$	-	8.7	-	S

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Electrical Characteristic, at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Dynamic Characteristic						
Input capacitance	C _{ies}	V _{CE} = 25V, V _{GE} = 0V f = 1000kHz	-	790	-	pF
Output capacitance	C _{oes}		-	41	-	
Reverse transfer capacitance	C _{res}		-	12	-	
Gate charge	Q _G	V _{CC} = 520V, I _C = 8.5A, V _{GE} = 15V	-	27.0	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L _E		-	7.0	-	nH

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at $T_{vj} = 25^{\circ}\text{C}$						
Turn-on delay time	$t_{d(\text{on})}$	$T_{vj} = 25^{\circ}\text{C},$ $V_{CC} = 400\text{V}, I_C = 8.5\text{A},$ $V_{GE} = 0.0/15.0\text{V},$ $R_{G(\text{on})} = 47.0\Omega, R_{G(\text{off})} = 47.0\Omega,$ $L\sigma = 30\text{nH}, C\sigma = 150\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include “tail” and diode reverse recovery.	-	30	-	ns
Rise time	t_r		-	18	-	ns
Turn-off delay time	$t_{d(\text{off})}$		-	106	-	ns
Fall time	t_f		-	46	-	ns
Turn-on energy	E_{on}		-	0.20	-	mJ
Turn-off energy	E_{off}		-	0.07	-	mJ
Total switching energy	E_{ts}		-	0.27	-	mJ

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at $T_{vj} = 150^{\circ}\text{C}$						
Turn-on delay time	$t_{d(\text{on})}$	$T_{vj} = 150^{\circ}\text{C},$ $V_{CC} = 400\text{V}, I_C = 8.5\text{A},$ $V_{GE} = 0.0/15.0\text{V},$ $R_{G(\text{on})} = 47.0\Omega, R_{G(\text{off})} = 47.0\Omega,$ $L\sigma = 30\text{nH}, C\sigma = 150\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include “tail” and diode reverse recovery.	-	27	-	ns
Rise time	t_r		-	18	-	ns
Turn-off delay time	$t_{d(\text{off})}$		-	123	-	ns
Fall time	t_f		-	72	-	ns
Turn-on energy	E_{on}		-	0.22	-	mJ
Turn-off energy	E_{off}		-	0.13	-	mJ
Total switching energy	E_{ts}		-	0.35	-	mJ

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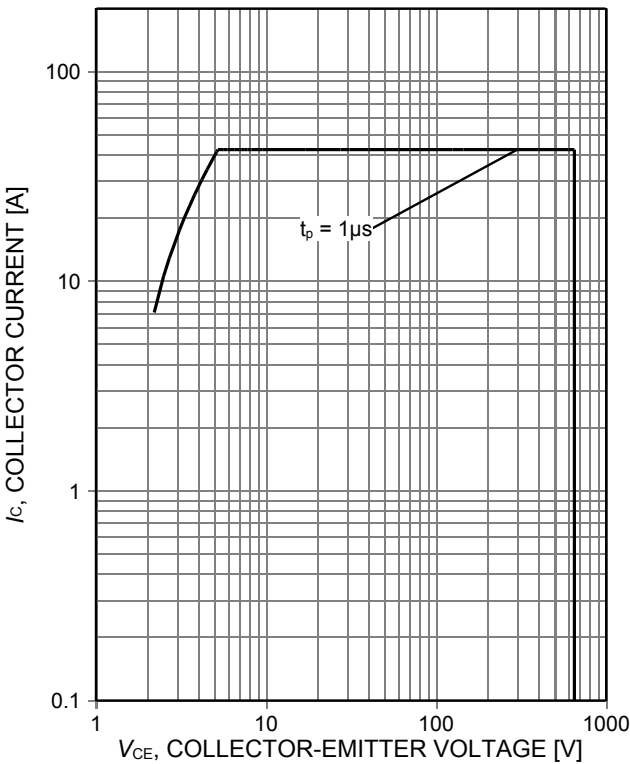


Figure 1. **Forward bias safe operating area**
($D=0$, $T_C=25^\circ\text{C}$, $T_{vj}\leq 175^\circ\text{C}$; $V_{GE}=15\text{V}$)

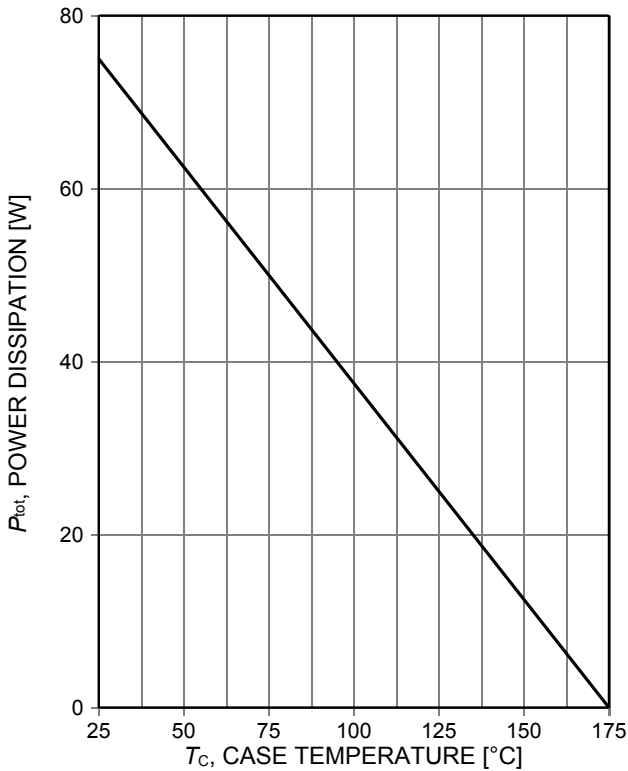


Figure 2. **Power dissipation as a function of case temperature**
($T_{vj}\leq 175^\circ\text{C}$)

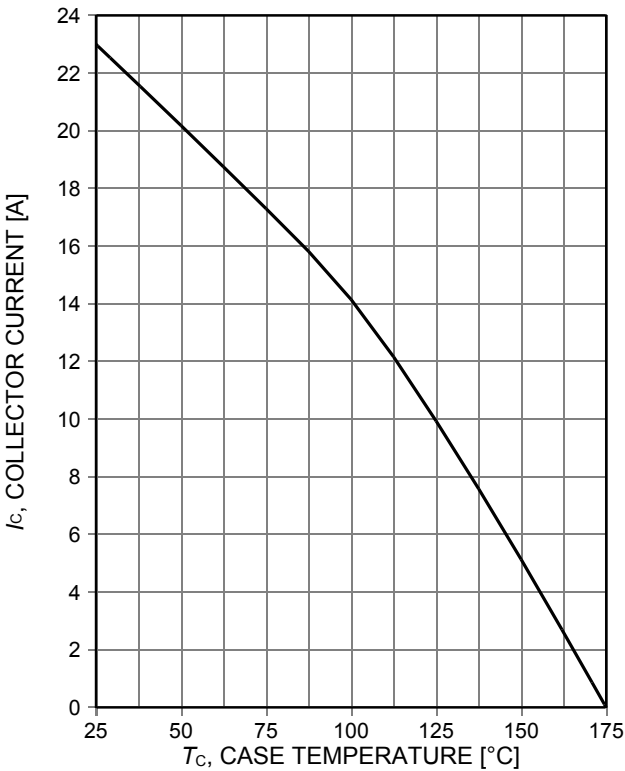


Figure 3. **Collector current as a function of case temperature**
($V_{GE}\geq 15\text{V}$, $T_{vj}\leq 175^\circ\text{C}$)

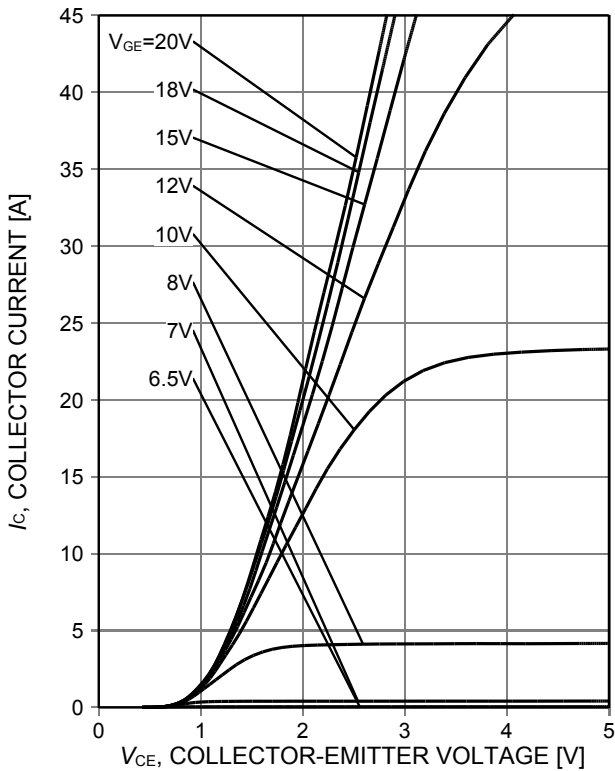


Figure 4. **Typical output characteristic**
($T_{vj}=25^\circ\text{C}$)

TRENCHSTOP™ IGBT6

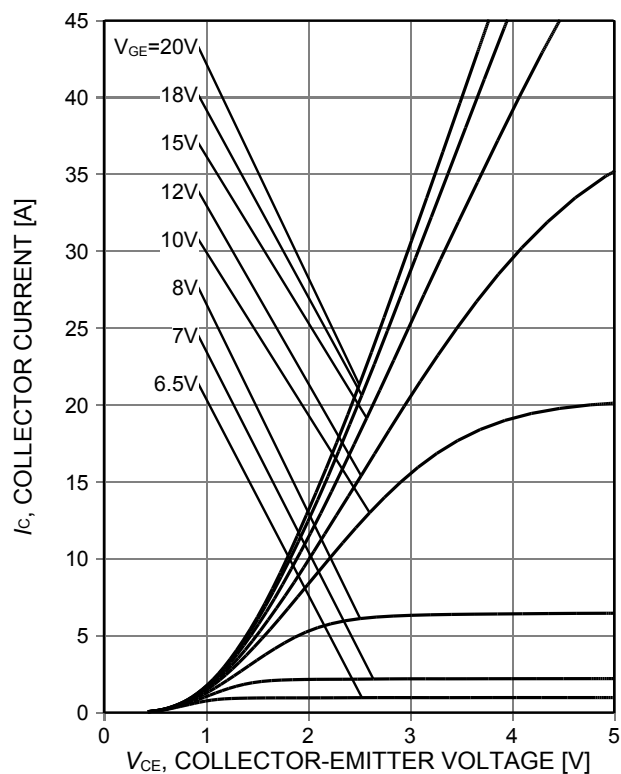


Figure 5. **Typical output characteristic**
($T_{vj}=150^{\circ}\text{C}$)

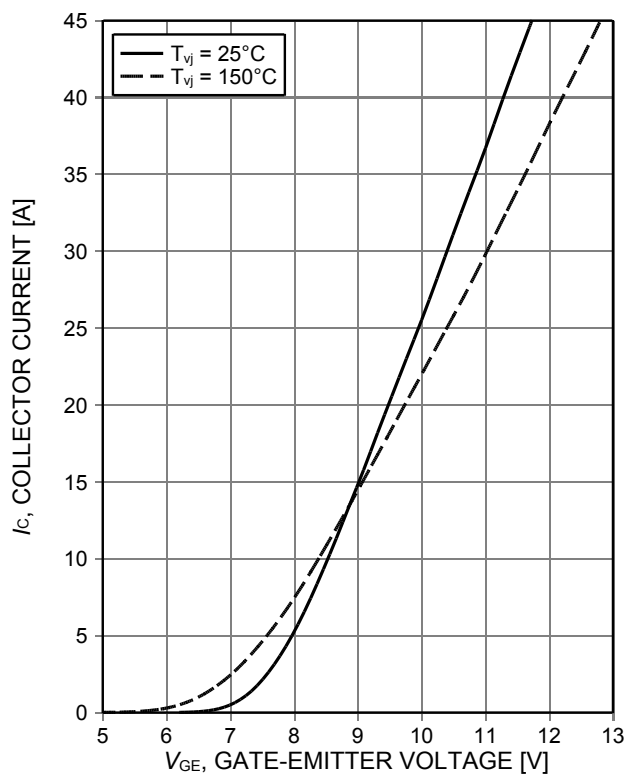


Figure 6. **Typical transfer characteristic**
($V_{ce}=20\text{V}$)

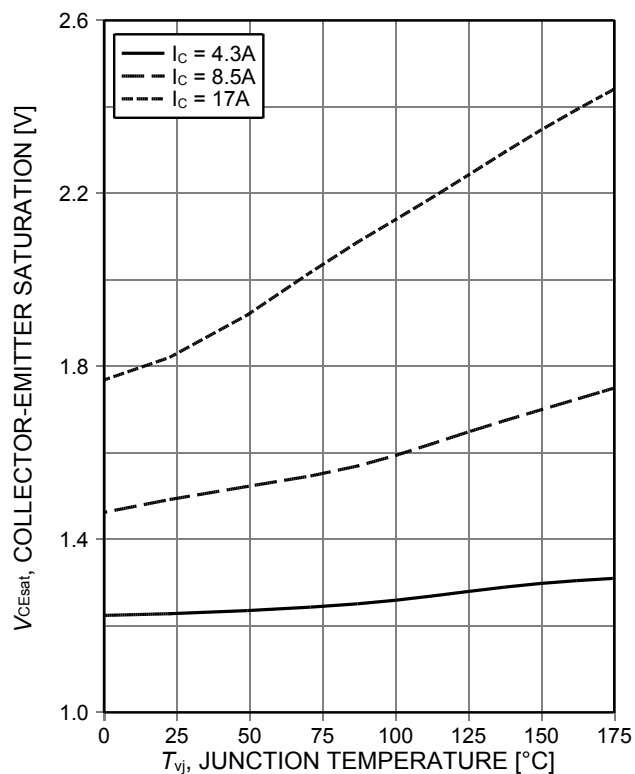


Figure 7. **Typical collector-emitter saturation voltage as a function of junction temperature**
($V_{ge}=15\text{V}$)

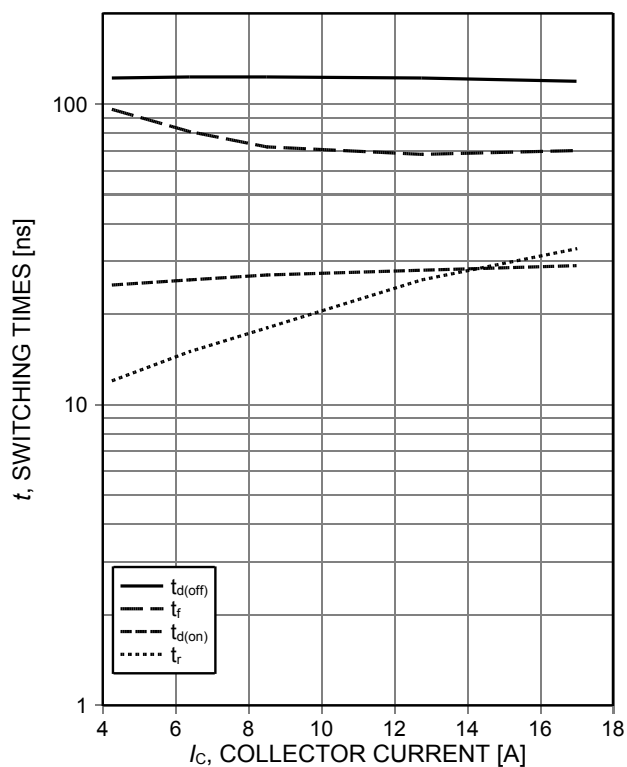


Figure 8. **Typical switching times as a function of collector current**
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{ce}=400\text{V}$, $V_{ge}=0/15\text{V}$, $r_g=47\Omega$, Dynamic test circuit in Figure E)

TRENCHSTOP™ IGBT6

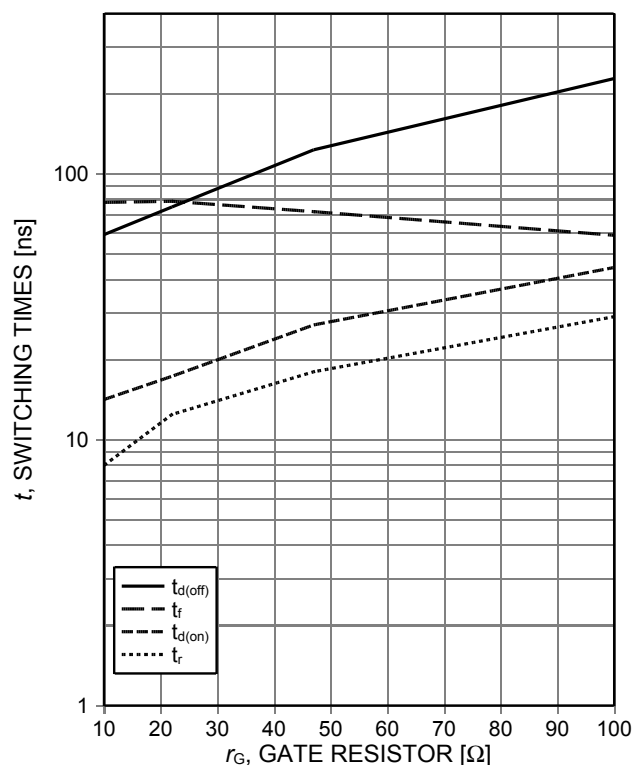


Figure 9. **Typical switching times as a function of gate resistor**
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=8.5\text{A}$, Dynamic test circuit in Figure E)

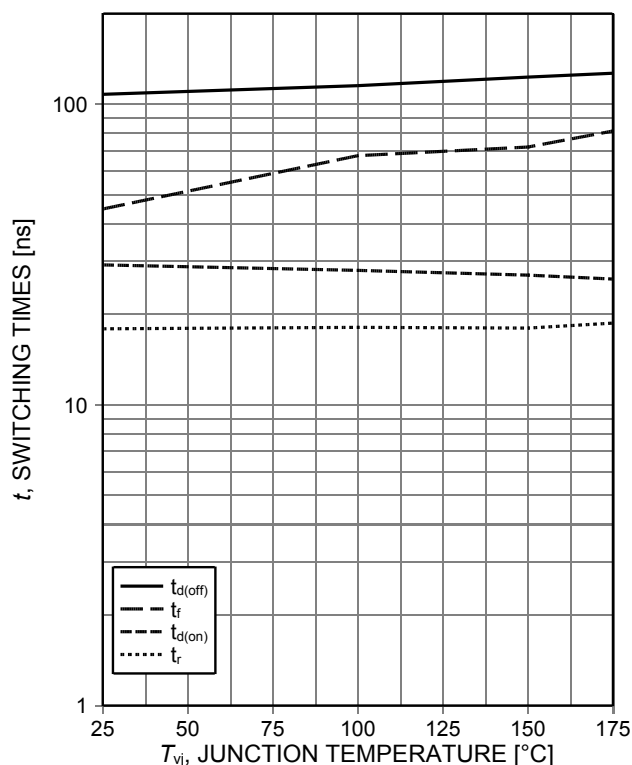


Figure 10. **Typical switching times as a function of junction temperature**
(inductive load, $V_{CE}=400\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=8.5\text{A}$, $r_G=47\Omega$, Dynamic test circuit in Figure E)

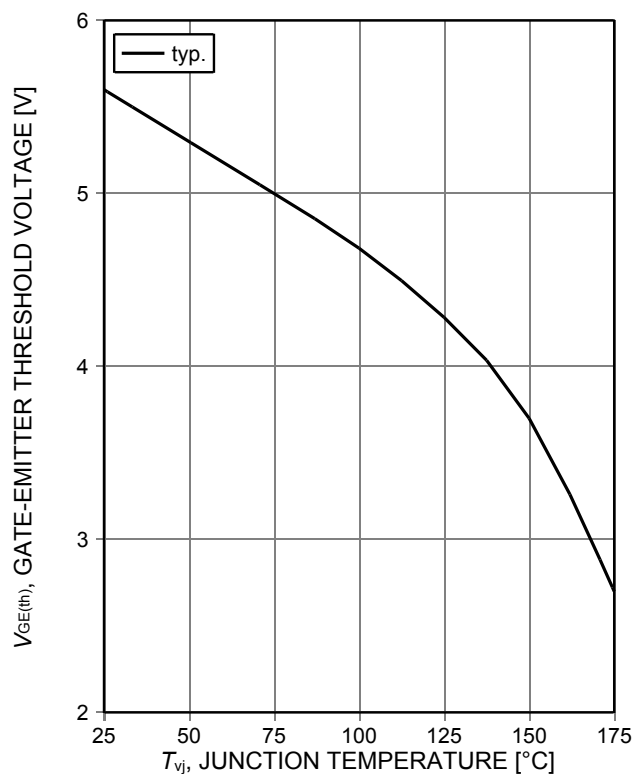


Figure 11. **Gate-emitter threshold voltage as a function of junction temperature**
($I_C=0.15\text{mA}$)

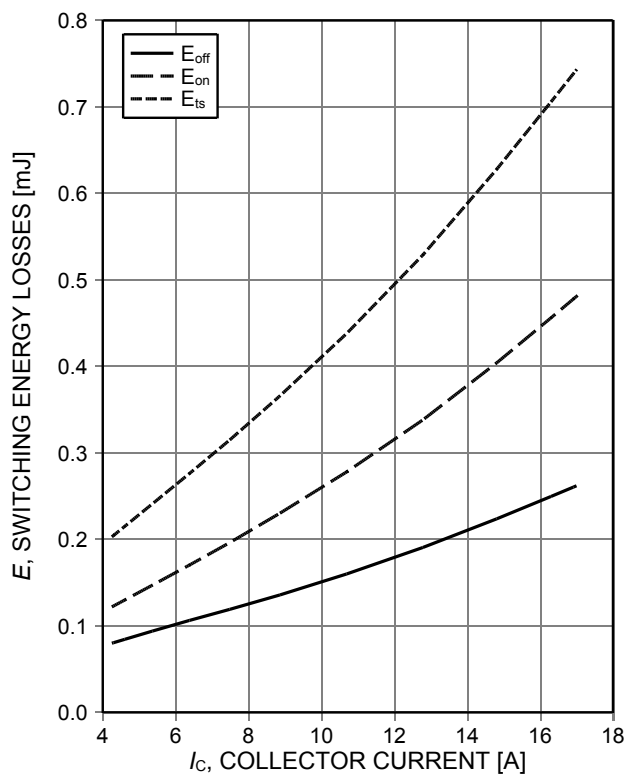


Figure 12. **Typical switching energy losses as a function of collector current**
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=0/15\text{V}$, $r_G=47\Omega$, Dynamic test circuit in Figure E)

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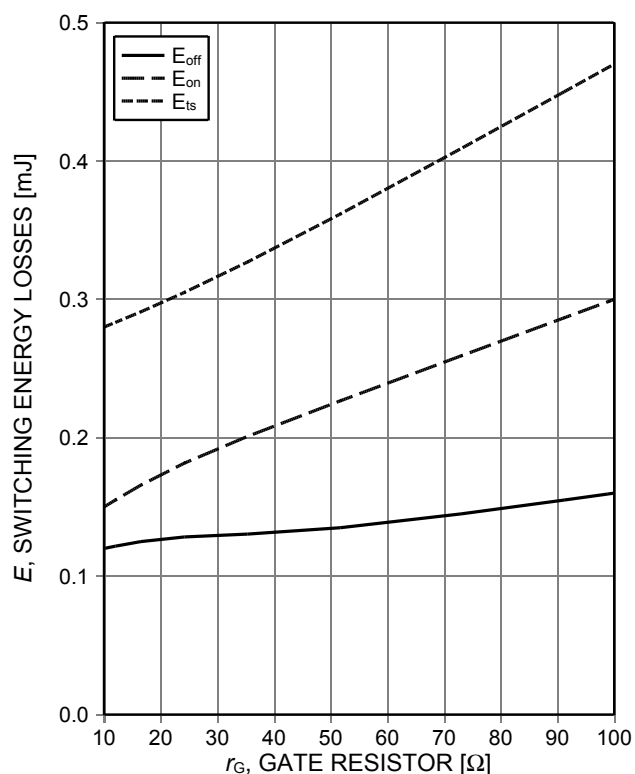


Figure 13. **Typical switching energy losses as a function of gate resistor**
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=8.5\text{A}$, Dynamic test circuit in Figure E)

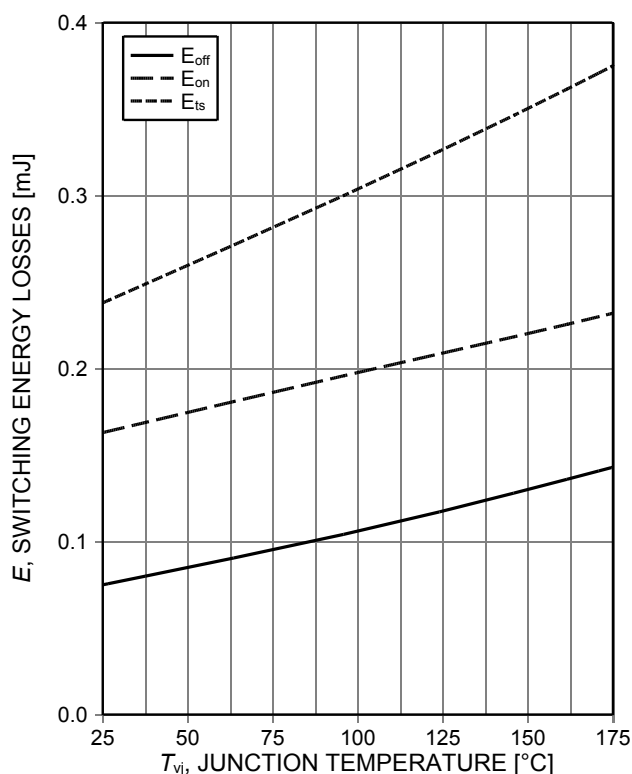


Figure 14. **Typical switching energy losses as a function of junction temperature**
(inductive load, $V_{CE}=400\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=8.5\text{A}$, $r_G=47\Omega$, Dynamic test circuit in Figure E)

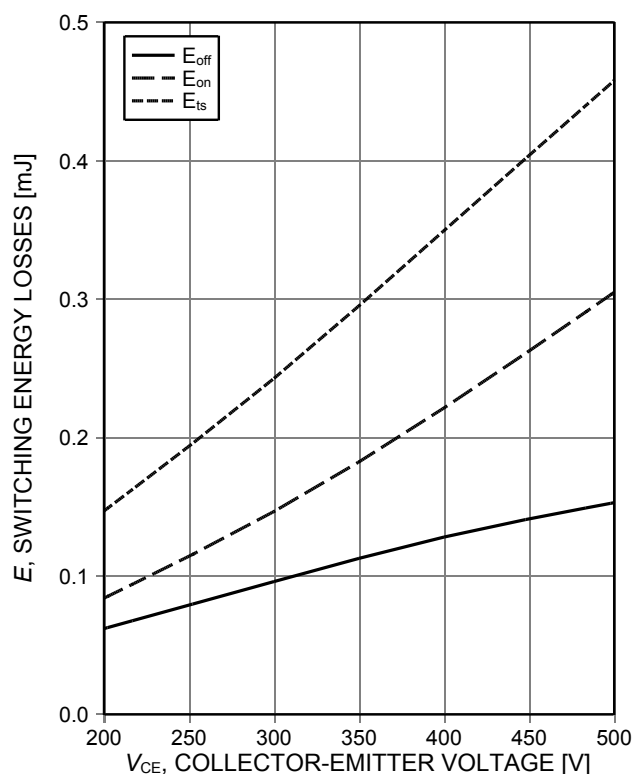


Figure 15. **Typical switching energy losses as a function of collector emitter voltage**
(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{GE}=0/15\text{V}$, $I_C=8.5\text{A}$, $r_G=47\Omega$, Dynamic test circuit in Figure E)

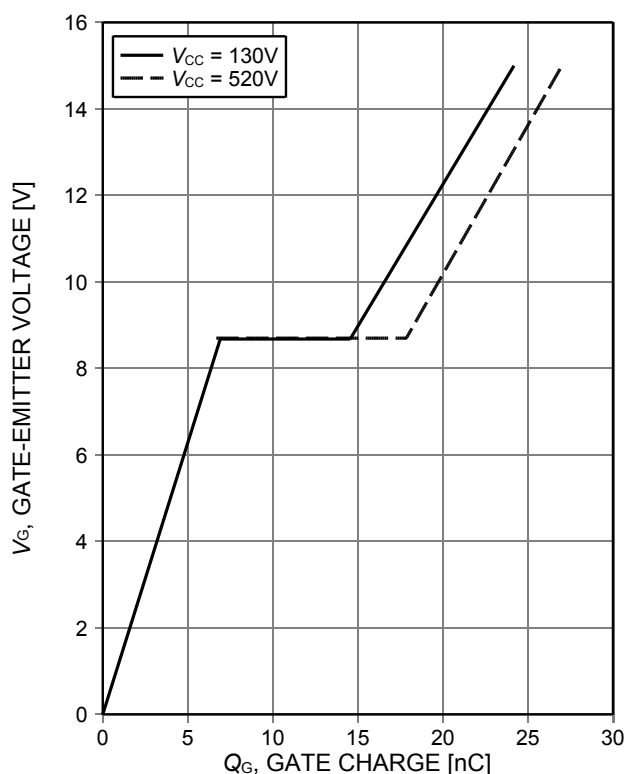


Figure 16. **Typical gate charge**
($I_C=8.5\text{A}$)

TRENCHSTOP™ IGBT6

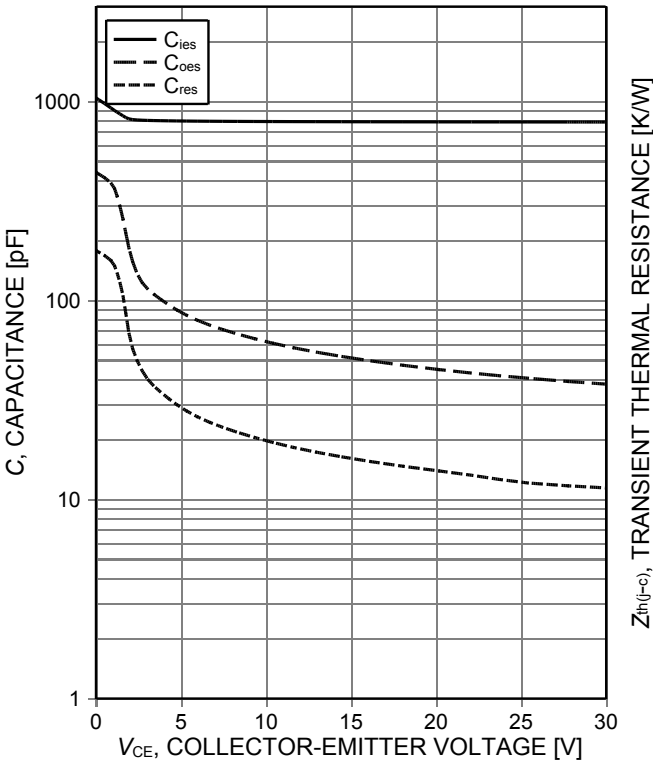


Figure 17. Typical capacitance as a function of collector-emitter voltage ($V_{GE}=0V$, $f=1MHz$)

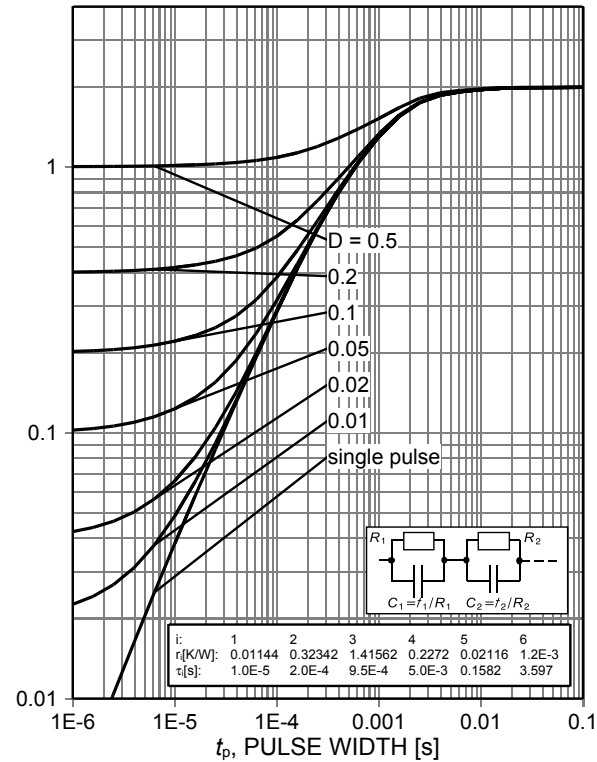
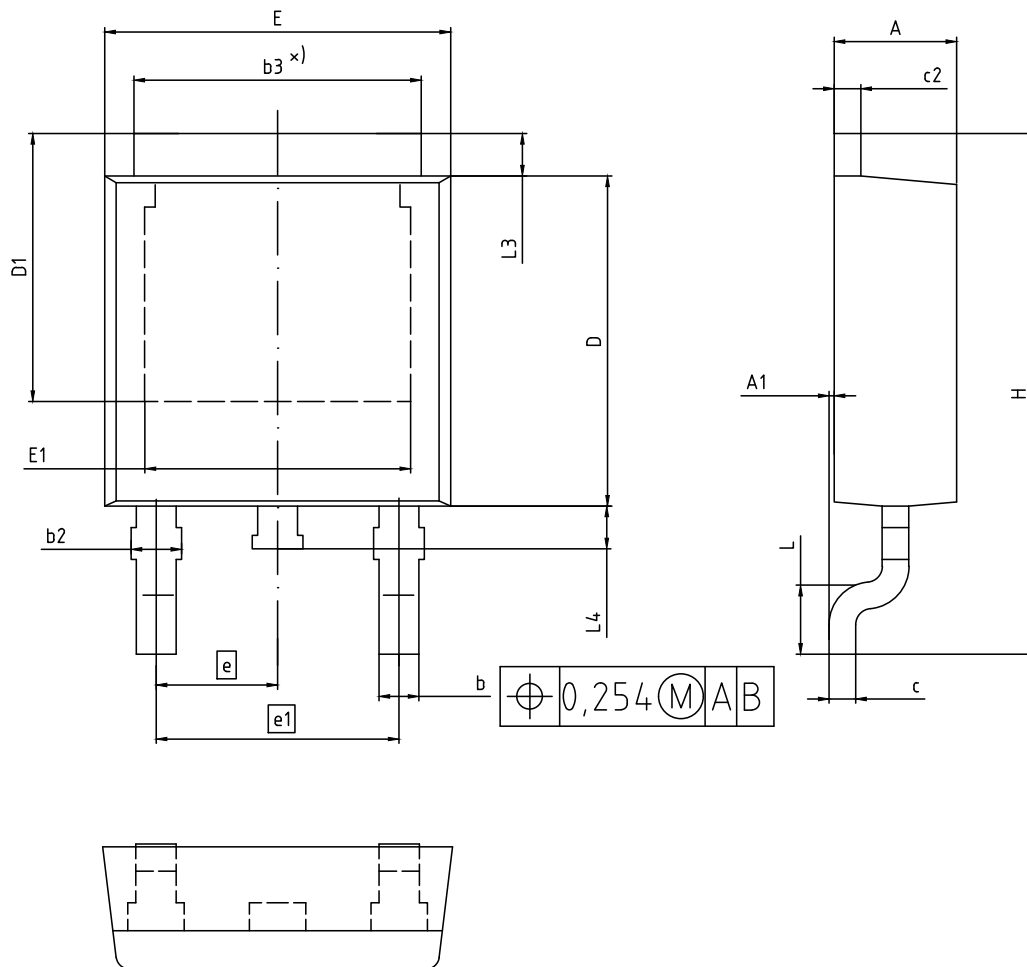


Figure 18. IGBT transient thermal resistance ($D=t_p/T$)

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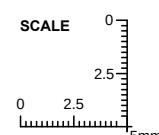
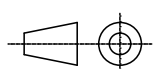
Package Drawing PG-TO252-3



NOTES:

1. ALL DIMENSIONS REFER TO JEDEC STANDARD TO-252 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

DIM	MILLIMETERS	
	MIN	MAX
A	2.16	2.41
A1	0.00	0.15
b	0.64	0.89
b2	0.65	1.15
b3	4.95	5.50
c	0.46	0.61
c2	0.40	0.98
D	5.97	6.22
D1	5.02	5.84
E	6.35	6.73
E1	4.32	5.21
e	2.29 (BSC)	
e1	4.57 (BSC)	
N	3	
H	9.40	10.48
L	1.18	1.78
L3	0.89	1.27
L4	0.51	1.02

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REVISION 06

Testing Conditions

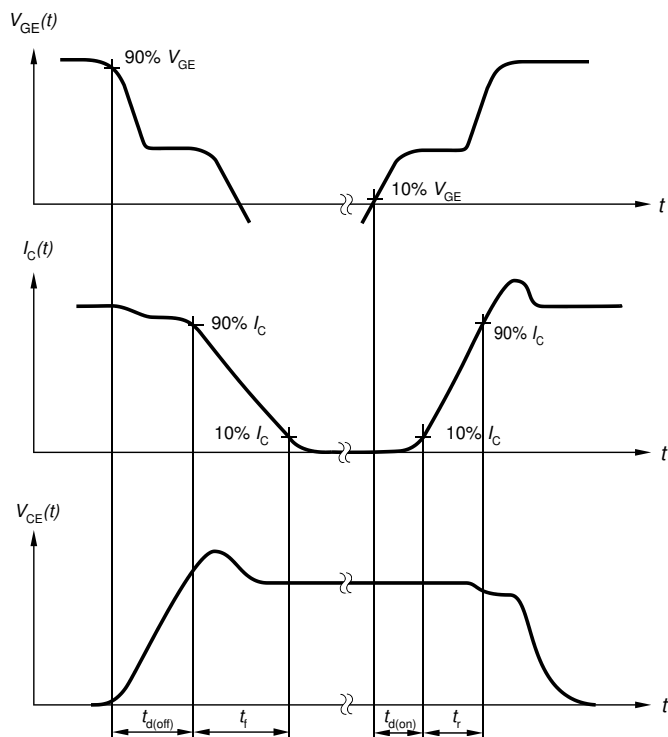


Figure A. Definition of switching times

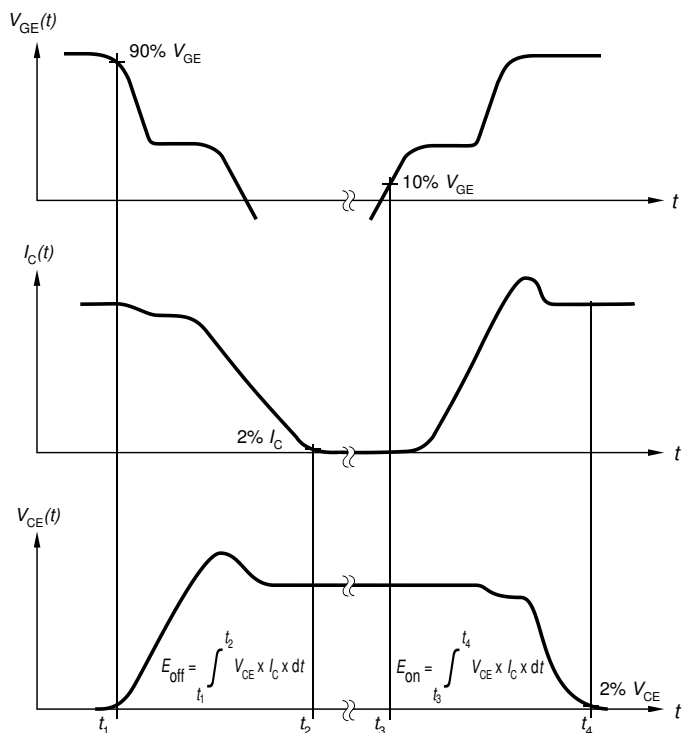


Figure B. Definition of switching losses

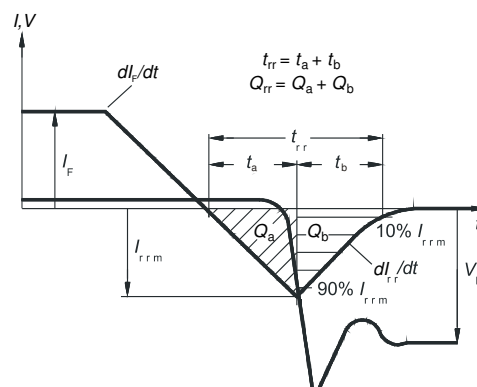


Figure C. Definition of diode switching characteristics

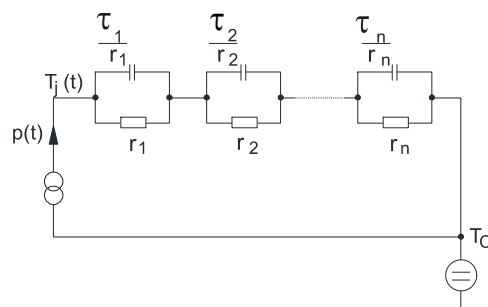


Figure D. Thermal equivalent circuit

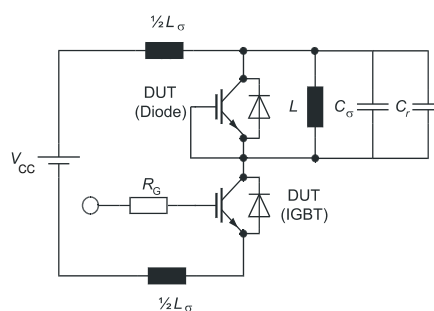


Figure E. **Dynamic test circuit**
Parasitic inductance L_σ ,
parasitic capacitor C_σ ,
relief capacitor C_r ,
(only for ZVT switching)

TRENCHSTOP™ IGBT6**Revision History**

IGD10N65T6**Revision: 2020-04-29, Rev. 2.3**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.1	2020-03-16	Final Data sheet
2.2	2020-04-20	Final
2.3	2020-04-29	Final

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